

Claim Amendments

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims

Claim 1. (Currently Amended) An electronic device, comprising:
a battery containing a nonaqueous ~~battery~~ solvent disposed on a substrate and an electronic circuit disposed adjacent to the battery, wherein the electronic circuit is isolated from the battery by an epoxy resin composition ~~containing~~ comprising:

- (a) an epoxy resin,
- (b) a latent catalyst consisting of a phenol compound and an organic metal compound,
- (c) a butyral resin, and
- (d) an inorganic filler.

Claim 2. (Currently Amended) ~~An~~ The electronic device according to Claim 1, wherein the average particle diameter of said inorganic filler is 10 μm or less and the ~~ratio~~ amount of the inorganic filler in said epoxy resin composition is 10 % by weight or more ~~and to~~ 80 % by weight or less.

Claim 3. (Currently Amended) ~~An~~ The electronic device according to Claim 1, wherein said organic metal compound is a metal complex.

Claim 4. (Currently Amended) ~~An~~ The electronic device according to Claim 1, wherein said phenol compound is a bisphenol S and said organic metal compound is ~~made of~~ a an organozirconium zirconium-type compound.

Claim 5. (Currently Amended) ~~An~~ The electronic device according to Claim 1, wherein said epoxy resin is an epoxy resin homopolymer.

Claim 6. (Currently Amended) ~~An~~ The electronic device according to Claim 2, wherein said organic metal compound is a metal complex.

Claim 7. (Currently Amended) ~~An~~ The electronic device according to Claim 2, wherein said phenol compound is a bisphenol S and said metal complex is ~~made of a~~ an organozirconium zirconium-type compound.

Claim 8. (Currently Amended) ~~An~~ The electronic device according to Claim 2, wherein said epoxy resin is an epoxy resin homopolymer.

Claim 9. (Withdrawn-Currently Amended) ~~An~~ The electronic device according to Claim 1, wherein said epoxy resin composition covers said electronic circuit.

Claim 10. (Currently Amended) ~~An~~ The electronic device according to Claim 1, wherein said epoxy resin composition covers said battery containing a nonaqueous solvent.

Claim 11. (Withdrawn-Currently Amended) ~~An~~ The electronic device according to Claim 1, wherein said epoxy resin composition is molded into the form of a container and the container encloses said battery containing a nonaqueous solvent.

Claim 12. (Withdrawn-Currently Amended) ~~An~~ The electronic device according to Claim 1, wherein said epoxy resin composition is molded into the form of a container and the container encloses said electronic circuit.

Claim 13. (Currently Amended) ~~An~~ The electronic device according to Claim 1, wherein said electronic circuit is a control circuit for ~~said~~ a secondary battery containing a nonaqueous solvent.

Claim 14. (Currently Amended) ~~An~~ The electronic device according to Claim 1, wherein said electronic circuit is a protective circuit for ~~said~~ a secondary battery containing a nonaqueous solvent.

Claim 15. (Currently Amended) An electronic device, comprising:
a battery containing ~~using~~ a nonaqueous electrolyte and a ~~battery~~ protective circuit for the battery arranged adjacent to the battery, the ~~battery~~ protective circuit for the battery being coated with an epoxy resin composition containing an epoxy resin, a latent catalyst consisting of a phenol compound and an organic metal compound, a butyral resin and an inorganic filler.

Claim 16. (Currently Amended) ~~An~~ The electronic device according to Claim 15, wherein the average particle diameter of said inorganic filler is 10 μm or less and the ~~ratio~~ amount of the inorganic filler in said epoxy resin composition is 10 % by weight or more ~~and~~ to 80 % by weight or less.

Claim 17. (Currently Amended) ~~An~~ The electronic device according to Claim 15,
wherein said organic metal compound is a metal complex.

Claim 18. (Currently Amended) ~~An~~ The electronic device according to Claim 15,
wherein said phenol compound is a bisphenol S and said organic metal compound is ~~made of~~
~~a~~ an organozirconium zirconium-type compound.

Claim 19. (Currently Amended) ~~An~~ The electronic device according to Claim ~~1~~ 15,
wherein said epoxy resin is an epoxy resin homopolymer.

Claim 20. (New) An electronic device, comprising:
a battery containing a nonaqueous solvent disposed on a substrate and an electronic
circuit disposed adjacent to the battery, wherein the electronic circuit is isolated from the
battery by an epoxy resin composition which covers the battery containing a nonaqueous
solvent comprising:

- (a) a bisphenol F epoxy resin,
- (b₁) a latent catalyst consisting of 4,4'-dihydroxydiphenylsulfone and
- (b₂) zirconium tetraacetylacetonate,
- (c) a butyral resin, and
- (d) silica.